

03-22-2002

Docket No.: FIS920010231US1

FORM PTO-1595 (Modified)
(Rev. 03-01)
OMB No. 0851-0027 (exp. 5/31/2002)
P08/REV03

ET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office



Tab settings → → → ▼ ▼ ▼ ▼ ▼

102028574

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jack A. Mandelman
Ronald G. Filippi
Jeffrey P. Gambino
Richard A. Wachnik

03/04/02

Additional names(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 02/19; 02/21; 03/05; 02/25/2002

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Internal Address: _____

Street Address: New Orchard Road

City: Armonk State: NY ZIP: 10504

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 02/19; 02/21; 03/05; 02/25/2002

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: H. Daniel Schnurmann

Internal Address: Intellectual Property Law Department

International Business Machines Corporation

Dept. 18G / Bldg. 300-482

Street Address: 2070 Route 52

03/21/2002 TDIAZ1 00000034 090458 10091643

01 FC:581

40.00 CH

City: Hopewell Junction

State: NY

ZIP: 12533

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☒ Authorized to be charged to deposit account

8. Deposit account number:

09-0458 FI-076

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

H. Daniel Schnurmann, Reg. No. 35,791

Name of Person Signing

Signature

March 6, 2002

Date

Total number of pages including cover sheet, attachments, and document: 6

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments

PATENT
REEL: 012694 FRAME: 0076

ASSIGNMENT

WHEREAS, we

(1) <u>Jack A. Mandelman</u>	of Stormville
County of Dutchess	State of New York
and	
(2) <u>Ronald G. Filippi</u>	of Wappingers Falls
County of Dutchess	State of New York
and	
(3) <u>Jeffrey P. Gambino</u>	of Westford
County of Chittenden	State of Vermont
and	
(4) <u>Richard A. Wachnik</u>	of Mt. Kisco
County of Westchester	State of New York

have invented certain improvements in

ELECTRICALLY POROUS ON-CHIP DECOUPLING/SHIELDING LAYER

and executed a United States patent application therefor on:
(dates that Inventors signed the declaration)

(1) 2-19-02, and (2) 2/21/02, and (3) _____, and (4) 2/25/02

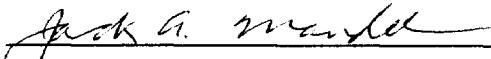
Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said

United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.


Signed

(1) at E. Fishkill, NY
on FEB 19 2002,
and



Jack A. Mandelman

(2) at E. Fishkill, NY
on 2/21/02,
and

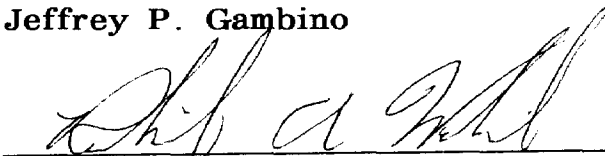


Ronald G. Filippi

(3) at Essex Junction, VT
on _____,
and

Jeffrey P. Gambino

(4) at E. Fishkill
on 2/25/2002,



Richard A. Wachnik

Docket No. FIS9-2001-0231-US1

ASSIGNMENT

WHEREAS, we

- | | |
|--|--|
| (1) <u>Jack A. Mandelman</u>
County of Dutchess
and | of Stormville
State of New York |
| (2) <u>Ronald G. Filippi</u>
County of Dutchess
and | of Wappingers Falls
State of New York |
| (3) <u>Jeffrey P. Gambino</u>
County of Chittenden
and | of Westford
State of Vermont |
| (4) <u>Richard A. Wachnik</u>
County of Westchester | of Mt. Kisco
State of New York |

have invented certain improvements in

ELECTRICALLY POROUS ON-CHIP DECOUPLING/SHIELDING LAYER

and executed a United States patent application therefor on:
(dates that Inventors signed the declaration)

- (1) _____, and (2) _____, and (3) 3/5/02, and (4) _____.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said

FIS9-2001-0231-US1

United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

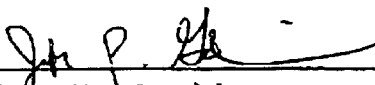
(1) at E. Fishkill, NY
on _____,
and

Jack A. Mandelman

(2) at E. Fishkill, NY
on _____,
and

Ronald G. Filippi

(3) at Essex Junction, VT
on 3/5/02,
and



Jeffrey P. Gambino

(4) at _____
on _____,

Richard A. Wachnik